

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

*In re* Application of: Virgil Cotoco Ararao, et al. : Confirmation No.: 6546  
Serial No.: 10/721,916 : Art Unit: 2813  
Filed: 11/24/2003 : Examiner: Thanh T. Nguyen  
For: FABRICATION METHOD :  
FOR SEMICONDUCTOR  
PACKAGE HEAT  
SPREADERS

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE AFTER FINAL REJECTION**

Sir/Madam:

The following Remarks are submitted in response to the Final Office Action mailed January 29, 2007. After this introductory section, there are Remarks starting on a separate page.

Reconsideration of the rejections is respectfully requested.